SYNCHRONOUS ETHERNET FREQUENCY TRANSLATOR
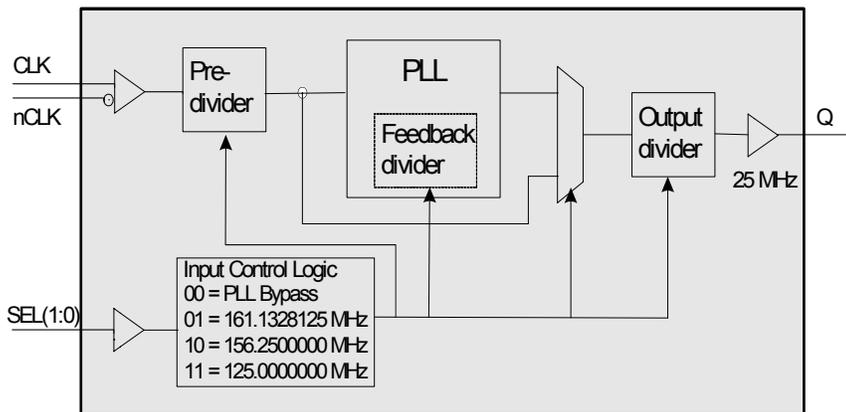
ICS840271I

General Description

The ICS840271I is a PLL-based Frequency Translator intended for use in telecommunication applications such as Synchronous Ethernet. The internal PLL translates Ethernet clock frequencies such as 125MHz (1Gb Ethernet), 156.25MHz (10GbE XAUI) and 161.1328MHz (10Gb Ethernet) to an output frequency of 25MHz. The PLL does not any require external components. The input frequency is selectable by a 2-pin interface. The ICS840271I is optimized for low cycle-to-cycle jitter on the 25MHz output signal. The input of the device accepts differential (LVPECL, LVDS, LVHSTL, SSTL, HCSL) or single-ended (LVCMOS) signals. The extended temperature range supports telecommunication and networking equipment requirements. The ICS840271I uses a small RoHS 6, 8-pin TSSOP package and is an effective solution for space-constrained applications.

Features

- Clock frequency translator for Synchronous Ethernet applications
- One single-ended output (LVCMOS or LVTTL levels), 16Ω output impedance
- Differential input pair (CLK, nCLK) accepts LVPECL, LVDS, LVHSTL, SSTL, HCSL input levels
- Supports input clock frequencies of: 125MHz, 156.25MHz or 161.1328MHz
- Generates a 25MHz output clock signal
- Internal resistor bias on nCLK pin allows the user to drive CLK input with external single-ended (LVCMOS/LVTTL) input levels
- Internal PLL is optimized for low cycle-to-cycle jitter at the output
- Full 3.3V or 2.5V supply voltage
- -40°C to 85°C ambient operating temperature
- Available in lead-free (RoHS 6) package

Block Diagram

Pin Assignment
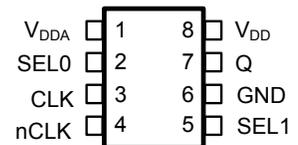
ICS840271I
8 Lead TSSOP
4.40mm x 3.0mm x 0.925mm
package body
G Package
Top View

Table 1. Pin Descriptions

Number	Name	Type		Description
1	V_{DDA}	Power		Analog supply pin.
2	SEL0	Input	Pulldown	Selects the input reference frequency and the PLL bypass mode. LVCMOS/LVTTL interface levels. See Table 3.
3	CLK	Input	Pulldown	Non-inverting differential clock input.
4	nCLK	Input	Pullup/ Pulldown	Inverting differential clock input. Internal resistor bias to V_{DD}/2.
5	SEL1	Input	Pullup	Selects the input reference frequency and the PLL bypass mode. LVCMOS/LVTTL interface levels. See Table 3.
6	GND	Power		Power supply ground.
7	Q	Output		Single-ended clock output. LVCMOS/LVTTL interface levels.
8	V_{DD}	Power		Core supply pin.

NOTE: *Pullup and Pulldown* refer to internal input resistors. See Table 2, *Pin Characteristics,* for typical values.

Table 2. Pin Characteristics

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
C_{IN}	Input Capacitance			4		pF
R_{PULLUP}	Input Pullup Resistor			51		kΩ
$R_{PULLDOWN}$	Input Pulldown Resistor			51		kΩ
R_{OUT}	Output Impedance	V_{DD} = 3.465V		16		Ω
		V_{DD} = 2.625V		19		Ω

Function Tables

Table 3. SEL[1:0] Function Table

Inputs				
SEL1	SEL0	CLK, nCLK (MHz)	Mode	Output (MHz)
0	0	REF	PLL Bypass	REF/ 5
0	1	161.1328125	PLL Enabled	25
1 (default)	0 (default)	156.25	PLL Enabled	25
1	1	125	PLL Enabled	25

NOTE: REF = Input clock signal frequency

Absolute Maximum Ratings

NOTE: Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These ratings are stress specifications only. Functional operation of product at these conditions or any conditions beyond those listed in the *DC Characteristics or AC Characteristics* is not implied. Exposure to absolute maximum rating conditions for extended periods may affect product reliability.

Item	Rating
Supply Voltage, V_{DD}	4.6V
Inputs, V_I	-0.5V to V_{DD} + 0.5V
Outputs, I_O (LVCMOS)	-0.5V to V_{DD} + 0.5V
Package Thermal Impedance, θ_{JA}	129.5°C/W (0 mps)
Storage Temperature, T_{STG}	-65°C to 150°C

DC Electrical Characteristics

Table 4A. Power Supply DC Characteristics, V_{DD} = 3.3V±5%, T_A = -40°C to 85°C

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
V_{DD}	Core Supply Voltage		3.135	3.3	3.465	V
V_{DDA}	Analog Supply Voltage		V_{DD} – 0.08	3.3	V_{DD}	V
I_{DD}	Power Supply Current				75	mA
I_{DDA}	Analog Supply Current				8	mA

Table 4B. Power Supply DC Characteristics, V_{DD} = 2.5V±5%, T_A = -40°C to 85°C

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
V_{DD}	Core Supply Voltage		2.375	2.5	2.625	V
V_{DDA}	Analog Supply Voltage		V_{DD} – 0.08	2.5	V_{DD}	V
I_{DD}	Power Supply Current				72	mA
I_{DDA}	Analog Supply Current				8	mA

Table 4C. LVCMOS/LVTTL DC Characteristics, V_{DD} = 3.3V±5% or 2.5V±5%, T_A = -40°C to 85°C

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Units
V_{IH}	Input High Voltage		V_{DD} = 3.3V	2		V_{DD} + 0.3	V
			V_{DD} = 2.5V	1.7		V_{DD} + 0.3	V
V_{IL}	Input Low Voltage		V_{DD} = 3.3V	-0.3		0.8	V
			V_{DD} = 2.5V	-0.3		0.7	V
I_{IH}	Input High Current	SEL1	V_{DD} = V_{IN} = 3.465V or 2.625V			5	µA
		SEL0	V_{DD} = V_{IN} = 3.465V or 2.625V			150	µA
I_{IL}	Input Low Current	SEL1	V_{DD} = 3.465V, V_{IN} = 0V	-150			µA
		SEL0	V_{DD} = 3.465V, V_{IN} = 0V	-5			µA
V_{OH}	Output High Voltage		V_{DD} = 3.465V, I_{OH} = 12mA	2.6			V
			V_{DD} = 2.625V, I_{OH} = 12mA	1.8			V
V_{OL}	Output Low Voltage		V_{DD} = 3.465V or 2.625V, I_{OL} = -12mA			0.5	V

Table 4D. Differential DC Characteristics, V_{DD} = 3.3V±5% or 2.5V±5%, T_A = -40°C to 85°C

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Units
I_{IH}	Input High Current	CLK/nCLK	V_{DD} = V_{IN} = 3.465V or 2.625V			150	µA
I_{IL}	Input Low Current	CLK	V_{DD} = 3.465V or 2.625V, V_{IN} = 0V	-5			µA
		nCLK	V_{DD} = 3.465V or 2.625V, V_{IN} = 0V	-150			µA
V_{PP}	Peak-to-Peak Voltage; NOTE 1			0.15		1.3	V
V_{CMR}	Common Mode Input Voltage; NOTE 1, 2			GND + 0.5		V_{DD} − 0.85	V

NOTE 1: V_{IL} should not be less than -0.3V.
NOTE 2: Common mode input voltage is defined as V_{IH}.

AC Electrical Characteristics

Table 5A. AC Characteristics, V_{DD} = 3.3V±5%, T_A = -40°C to 85°C

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
f_{OUT}	Output Frequency			25		MHz
$f_{jit(cc)}$	Cycle-to-Cycle Jitter	SEL0 ≠ SEL1			40	ps
		SEL0 = SEL1 = 1			15	ps
t_{LOCK}	PLL Lock Time	SEL1 = 0, SEL0 = 1			1	s
		SEL 1 = 1, SEL0 = X			50	ms
t_R / t_F	Output Rise/Fall Time	20% to 80%	200		700	ps
odc	Output Duty Cycle		47		53	%

NOTE: Electrical parameters are guaranteed over the specified ambient operating temperature range, which is established when the device is mounted in a test socket with maintained transverse airflow greater than 500 lfpm. The device will meet specifications after thermal equilibrium has been reached under these conditions.

Table 5B. AC Characteristics, V_{DD} = 2.5V±5%, T_A = -40°C to 85°C

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
f_{OUT}	Output Frequency			25		MHz
$f_{jit(cc)}$	Cycle-to-Cycle Jitter	SEL0 ≠ SEL1			50	ps
		SEL0 = SEL1 = 1			15	ps
t_{LOCK}	PLL Lock Time	SEL1 = 0, SEL0 = 1			1	s
		SEL 1 = 1, SEL0 = X			50	ms
t_R / t_F	Output Rise/Fall Time	20% to 80%	200		700	ps
odc	Output Duty Cycle		47		53	%

NOTE: Electrical parameters are guaranteed over the specified ambient operating temperature range, which is established when the device is mounted in a test socket with maintained transverse airflow greater than 500 lfpm. The device will meet specifications after thermal equilibrium has been reached under these conditions.
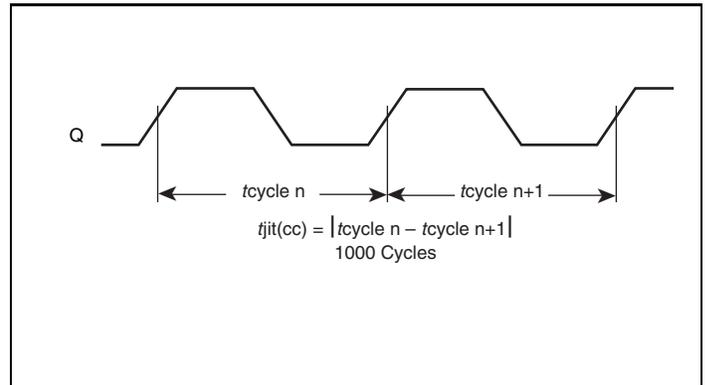
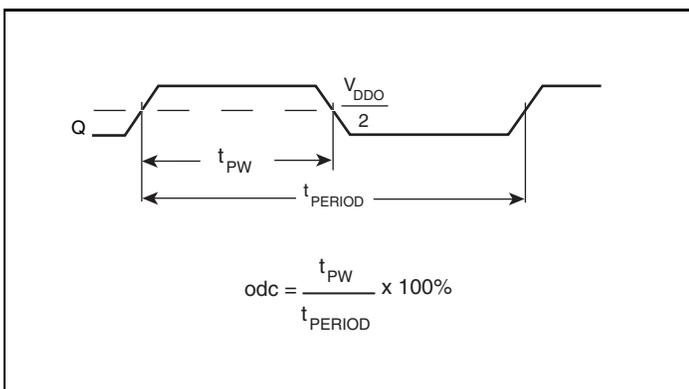# Parameter Measurement Information
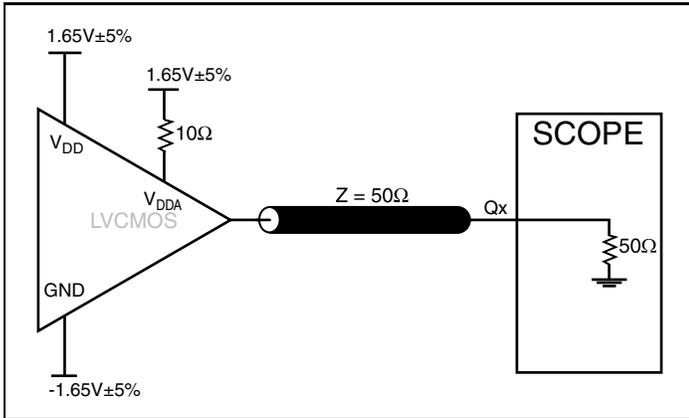
3.3V Output Load AC Test Circuit
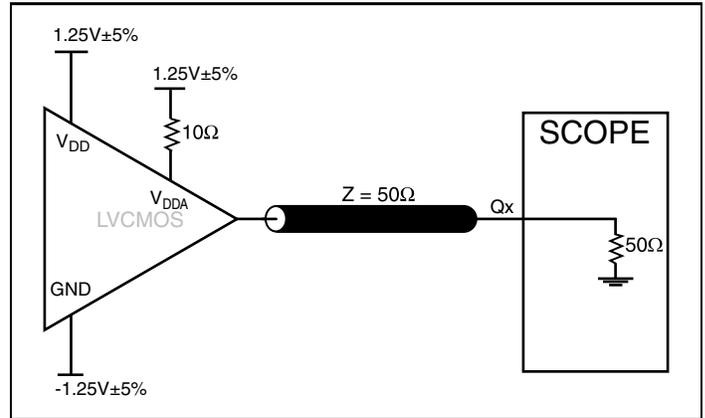
2.5V Output Load AC Test Circuit
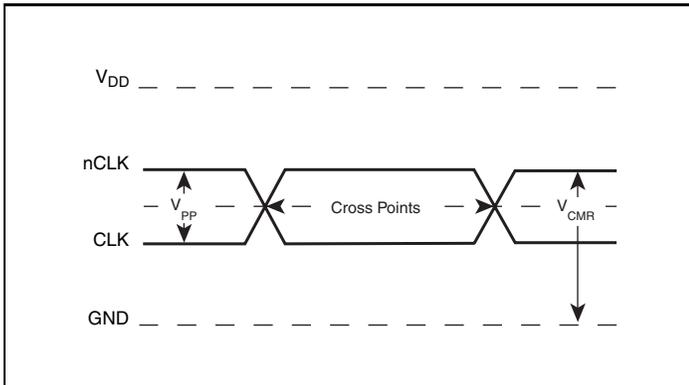
Differential Input Level

Cycle-to-Cycle Jitter

$$tjit(cc) = \frac{\left| tcycle\ n - tcycle\ n+1 \right|}{1000\ Cycles}$$

Output Duty Cycle/Pulse Width/Period

$$odc = \frac{t_{PW}}{t_{PERIOD}} \times 100\%$$
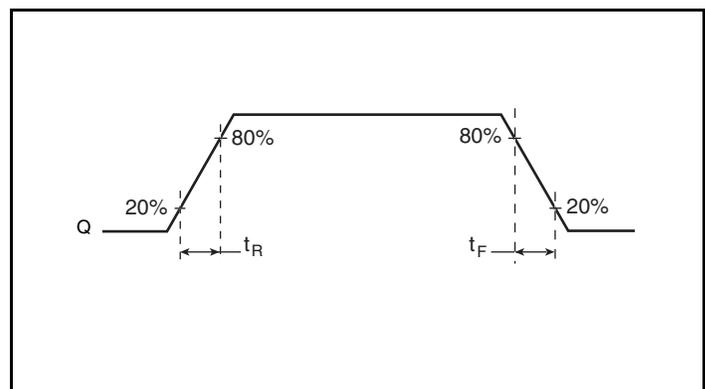
Output Rise/Fall Time

Application Information

Power Supply Filtering Technique

As in any high speed analog circuitry, the power supply pins are vulnerable to random noise. To achieve optimum jitter perform-ance, power supply isolation is required. The ICS840271I provides separate power supplies to isolate any high switching noise from the outputs to the internal PLL. V_{DD} and V_{DDA} should be individual-ly connected to the power supply plane through vias, and 0.01μF bypass capacitors should be used for each pin. *Figure 1* illustrates this for a generic V_{DD} pin and also shows that V_{DDA} requires that an additional 10Ω resistor along with a 10μF bypass capacitor be connected to the V_{DDA} pin.
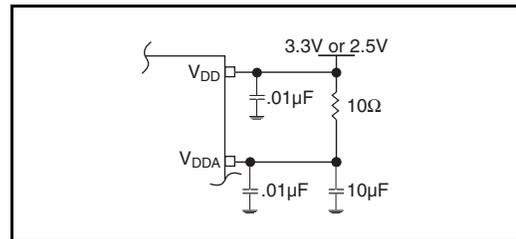
Figure 1. Power Supply Filtering

Wiring the Differential Input to Accept Single Ended Levels

Figure 2 shows how the differential input can be wired to accept single ended levels. The reference voltage V_REF = V_{DD}/2 is generated by the bias resistors R1, R2 and C1. This bias circuit should be located as close as possible to the input pin. The ratio of R1 and R2 might need to be adjusted to position the V_REF in the center of the input voltage swing. For example, if the input clock swing is only 2.5V and V_{DD} = 3.3V, V_REF should be 1.25V and R2/R1 = 0.609.
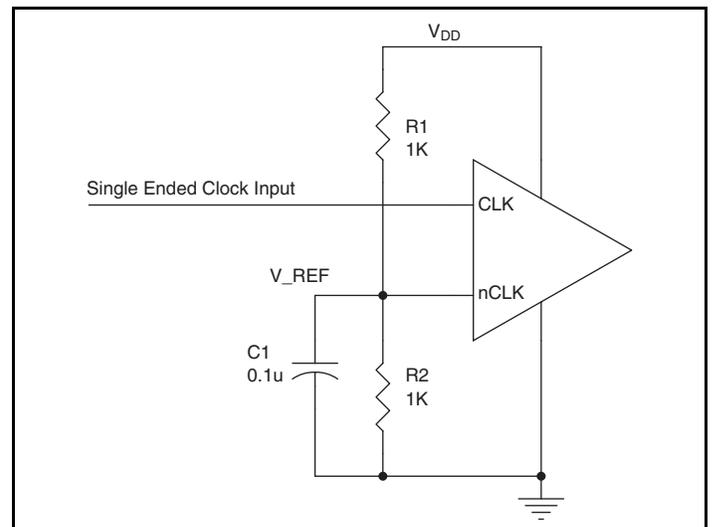
Figure 2. Single-Ended Signal Driving Differential Input

Recommendations for Unused Input Pins

Inputs:

LVCMOS Control Pins

All control pins have internal pullups or pulldowns; additional resistance is not required but can be added for additional protection. A 1kΩ resistor can be used.

Differential Clock Input Interface

The CLK /nCLK accepts LVDS, LVPECL, LVHSTL, SSTL, HCSL and other differential signals. Both signals must meet the V_{PP} and V_{CMR} input requirements. *Figures 3A to 3F* show interface examples for the HiPerClockS CLK/nCLK input driven by the most common driver types. The input interfaces suggested here are examples only. Please consult with the vendor of the driver component to confirm the driver termination requirements. For example, in Figure 3A, the input termination applies for IDT HiPerClockS open emitter LVHSTL drivers. If you are using an LVHSTL driver from another vendor, use their termination recommendation.
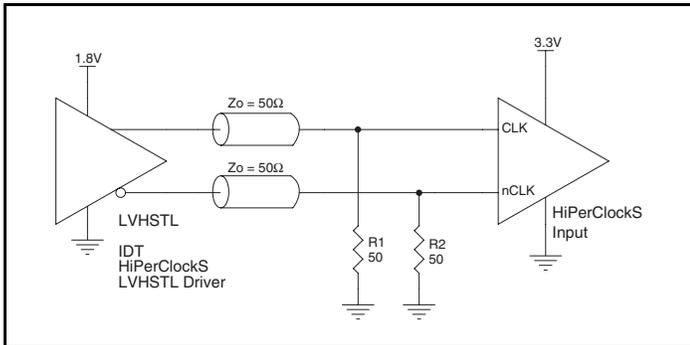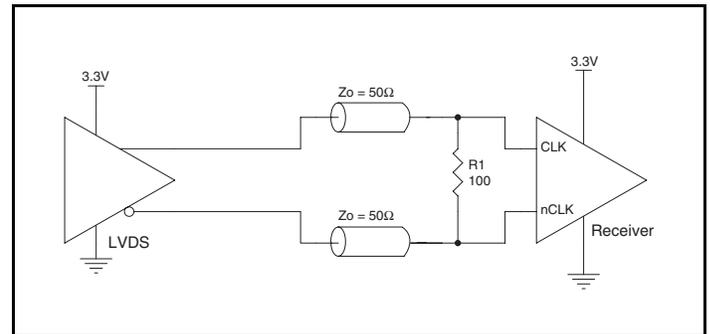

**Figure 3A. HiPerClockS CLK/nCLK Input
Driven by an IDT Open Emitter
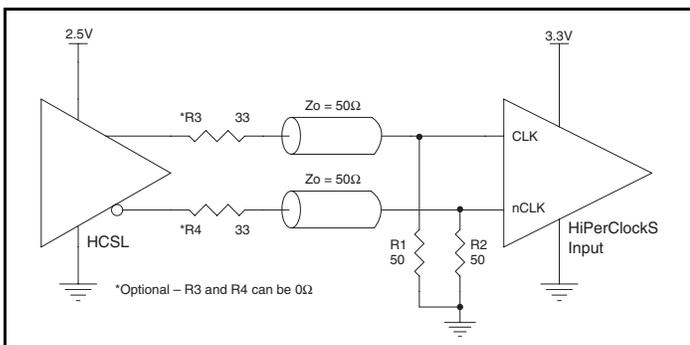HiPerClockS LVHSTL Driver**
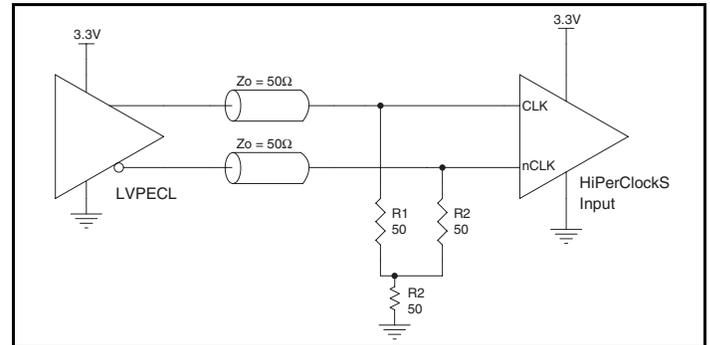
**Figure 3B. HiPerClockS CLK/nCLK Input
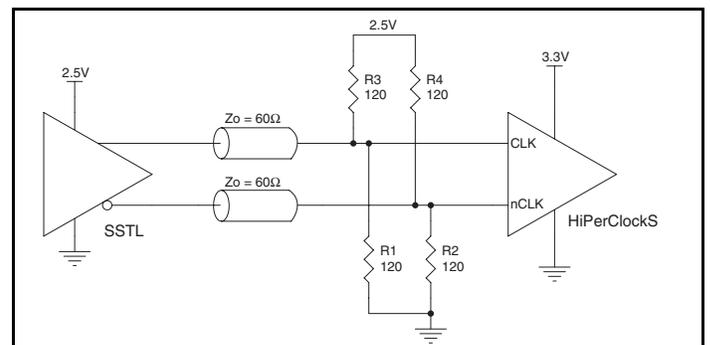Driven by a 3.3V LVPECL Driver**
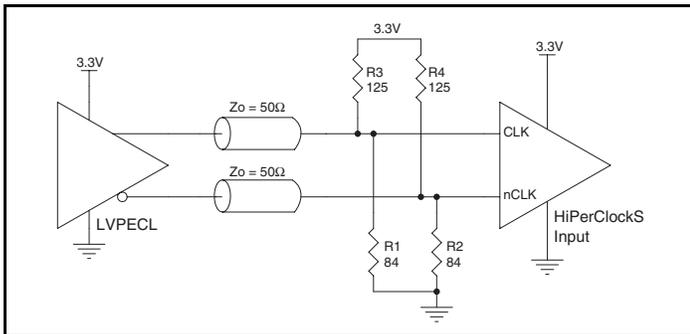
**Figure 3C. HiPerClockS CLK/nCLK Input
Driven by a 3.3V LVPECL Driver**

**Figure 3D. HiPerClockS CLK/nCLK Input
Driven by a 3.3V LVDS Driver**

**Figure 3E. HiPerClockS CLK/nCLK Input
Driven by a 3.3V HCSL Driver**

**Figure 3F. HiPerClockS CLK/nCLK Input
Driven by a 2.5V SSTL Driver**

Schematic Example

Figure 4 shows an example of ICS840271I applications schematic. In this example, the device is operated at V_{DD} = 3.3V. The input is driven by either a 3.3V LVPECL or LVDS driver. One example of

LVCMOS termination is shown in this schematic. The decoupling capacitors should be located a close as possible to the power pin.
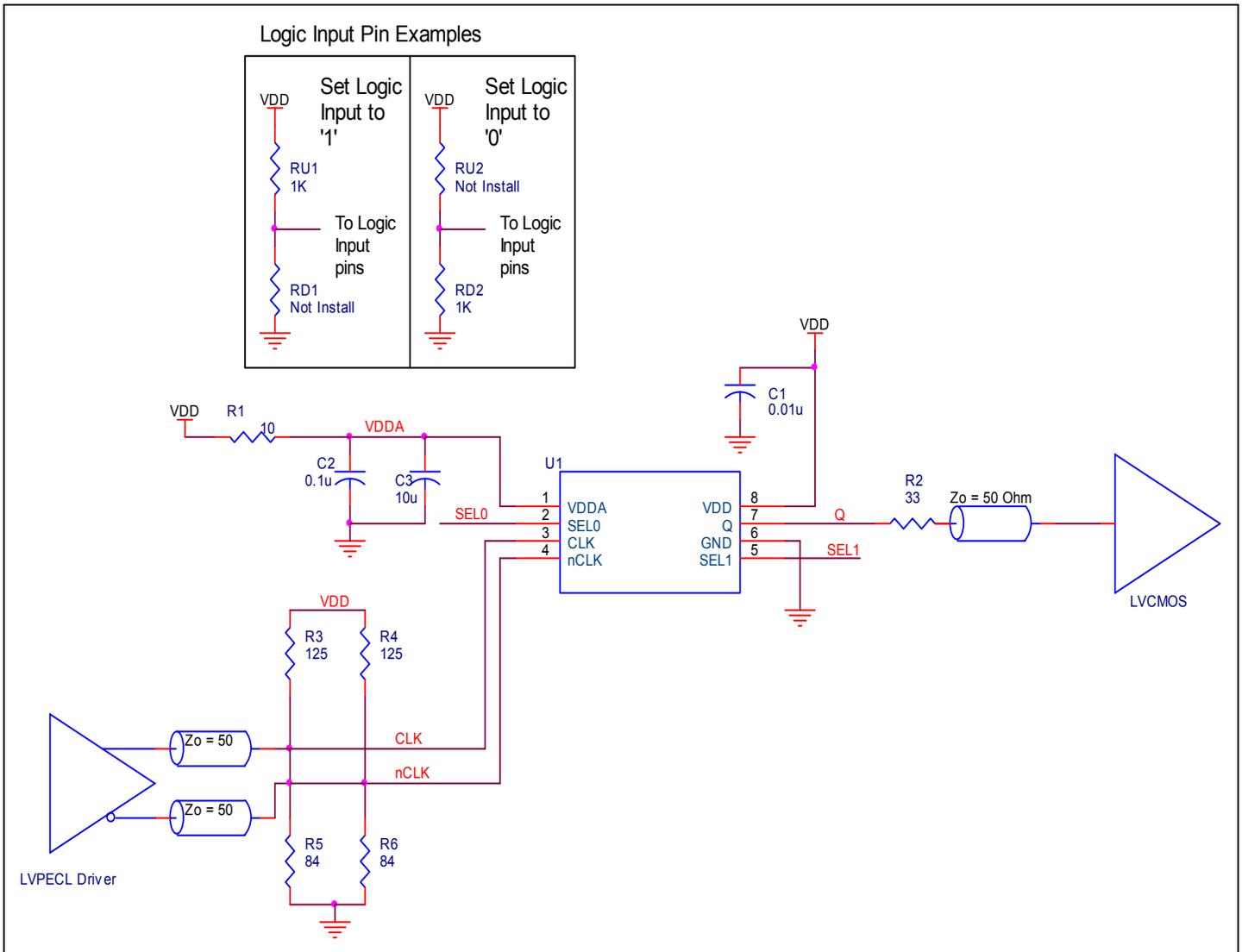

Figure 4. ICS840271I Schematic layout

Power Considerations

This section provides information on power dissipation and junction temperature for the ICS840271I.
Equations and example calculations are also provided.

1. Power Dissipation.

The total power dissipation for the ICS840271I is the sum of the core power plus the analog power plus the power dissipated in the load(s).
The following is the power dissipation for V_{DD} = 3.3V + 5% = 3.465V, which gives worst case results.

- Power (core)$_{MAX}$ = V_{DD_MAX} * (I_{DD} + I_{DDA}) = 3.465V *(75mA + 8mA) = **287.6mW**

- Output Impedance R_{OUT} Power Dissipation due to Loading 50Ω to V_{DD}/2
  Output Current I_{OUT} = V_{DD_MAX} / [2 * (50Ω + R_{OUT})] = 3.465V / [2 * (50Ω + 16Ω)] = **26.25mA**

- Power Dissipation on the R_{OUT} per LVCMOS output
  Power (R_{OUT}) = R_{OUT} * (I_{OUT})^2 = 16Ω * (26.25mA)^2 = **11mW per output**

Total Power Dissipation

- **Total Power**
  = Power (core)$_{MAX}$ + Total Power (R_{OUT})
  = 287.6mW + 11mW
  = 298.6mW

2. Junction Temperature.

Junction temperature, Tj, is the temperature at the junction of the bond wire and bond pad and directly affects the reliability of the device.
The maximum recommended junction temperature for HiPerClockS devices is 125°C.

> The equation for Tj is as follows: Tj = θ_{JA} * Pd_total + T_A

> Tj = Junction Temperature

> θ_{JA} = Junction-to-Ambient Thermal Resistance

> Pd_total = Total Device Power Dissipation (example calculation is in section 1 above)

> T_A = Ambient Temperature

In order to calculate junction temperature, the appropriate junction-to-ambient thermal resistance θ_{JA} must be used. Assuming no air flow and a multi-layer board, the appropriate value is 129.5°C/W per Table 6 below.

Therefore, Tj for an ambient temperature of 85°C with all outputs switching is:

> 85°C + 0.299W *129.5°C/W = 123.7°C. This is below the limit of 125°C.

This calculation is only an example. Tj will obviously vary depending on the number of loaded outputs, supply voltage, air flow and the type of board (multi-layer).

Table 6. Thermal Resistance θ_{JA} for 8 Lead TSSOP, Forced Convection

θ_{JA} by Velocity			
Meters per Second	**0**	**1**	**2.5**
Multi-Layer PCB, JEDEC Standard Test Boards	129.5°C/W	125.5°C/W	123.5°C/W

Reliability Information

Table 7. θ_{JA} vs. Air Flow Table for a 8 Lead TSSOP

θ_{JA} vs. Air Flow			
Meters per Second	**0**	**1**	**2.5**
Multi-Layer PCB, JEDEC Standard Test Boards	129.5°C/W	125.5°C/W	123.5°C/W

Transistor Count

The transistor count for ICS840271I is: 2732

Package Outline and Package Dimensions
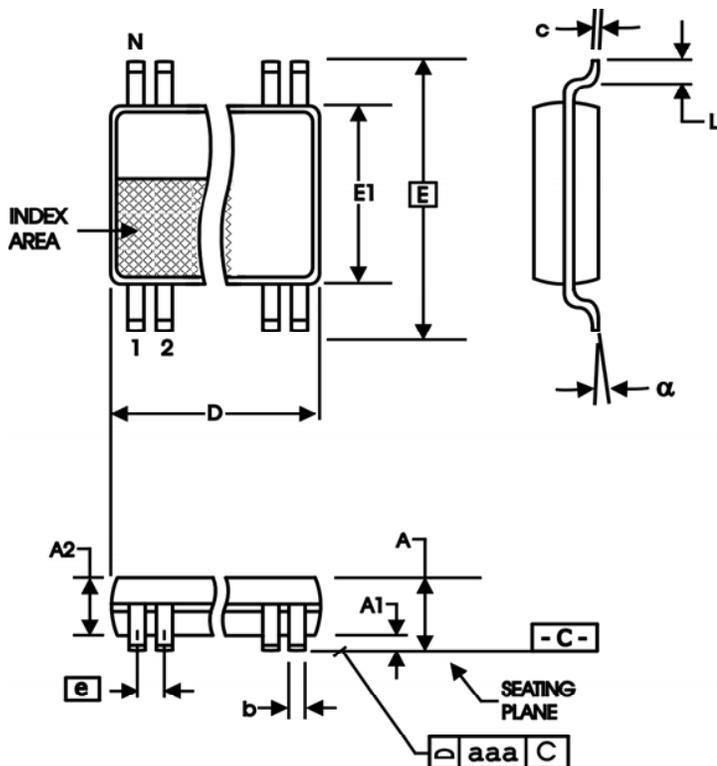
Package Outline - G Suffix for 8 Lead TSSOP

Table 8. Package Dimensions

All Dimensions in Millimeters		
Symbol	**Minimum**	**Maximum**
N	8	
A		1.20
A1	0.5	0.15
A2	0.80	1.05
b	0.19	0.30
c	0.09	0.20
D	2.90	3.10
E	6.40 Basic	
E1	4.30	4.50
e	0.65 Basic	
L	0.45	0.75
α	0°	8°
aaa		0.10

Reference Document: JEDEC Publication 95, MO-153

Ordering Information

Table 9. Ordering Information

Part/Order Number	Marking	Package	Shipping Packaging	Temperature
840271BGILF	71BIL	"Lead-Free" 8 Lead TSSOP	Tube	-40°C to 85°C
840271BGILFT	71BIL	"Lead-Free" 8 Lead TSSOP	2500 Tape & Reel	-40°C to 85°C

NOTE: Parts that are ordered with an "LF" suffix to the part number are the Pb-Free configuration and are RoHS compliant.

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